

heat conduction paths provided in the through holes of the circuit board and adapted to connect the electronic component and the heat radiating apparatus.

2. The electronic equipment of claim 1, wherein the plurality of through holes located in the area are formed in the circuit board, and the heat conduction path is provided for each of the plurality of through holes.

3. The electronic equipment of claim 2, wherein the circuit board has a circuit pattern, and an electric wire included in the circuit pattern is formed between two adjacent through holes of the plurality of through holes.

4. The electronic equipment of claim 1, wherein the circuit board includes:

a plurality of layers;

a plurality of circuit patterns formed in each of the plurality of layers; and

a connecting hole adapted to penetrate the circuit board and electrically connect the plurality of circuit patterns, and

when viewed from top, the through hole is larger in size than the connecting hole.

5. The electronic equipment of claim 1, wherein the circuit board includes:

a plurality of layers;

a plurality of circuit patterns formed in each of the plurality of layers; and

a connecting hole adapted to penetrate the circuit board and electrically connect the plurality of circuit patterns, and

when viewed from top, the through hole is substantially the same size as the connecting hole.

6. The electronic equipment of claim 1, wherein the electronic component is an integrated circuit apparatus,

the integrated circuit apparatus has a heat conduction portion on a surface facing the circuit board, and when the circuit board is viewed from top, the through hole is larger in size than half the heat conduction portion.

7. The electronic equipment of claim 1, wherein an electric circuit is formed in the circuit board, and the heat conduction path includes a material having a higher electric resistance than that of the electric circuit.

8. The electronic equipment of claim 1, wherein an electric circuit is formed in the circuit board, and the heat conduction path is formed of the same material as the electric circuit.

9. The electronic equipment of claim 1, wherein the heat conduction path is plating formed inside the through hole.

10. The electronic equipment of claim 1, wherein the electronic component is an integrated circuit apparatus,

the integrated circuit apparatus has a heat conduction portion on a surface facing the circuit board, and the heat conduction path is connected to the heat conduction portion.

11. The electronic equipment of claim 1, wherein at least a heat conduction sheet or thermal grease is disposed between the heat radiating member and the heat conduction path.

12. The electronic equipment of claim 1, wherein the circuit board has, on the second surface, a metal layer connected to the heat conduction path of the through hole and formed integrally with the circuit board.

13. The electronic equipment of claim 1, wherein another component is disposed on an opposite side of the heat radiating apparatus with the circuit board and the electronic component provided therebetween, and a distance between the another component and the electronic component is smaller than a thickness of the heat radiating apparatus in a direction of thickness of the circuit board.

14. The electronic equipment of claim 1, wherein the heat conduction path includes a material having a higher thermal conductivity than a base material of the circuit board, and the material fills the through hole.

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